IPC ASSOCIATION CONNECT ELECTRONICS INDUST.	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			ler both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					ials and Mfg Information				
upplier Infor	mation														
Company name*			Company unique ID			J	Unique ID Authority				Response Date*				
nsemi											2023-06-08				
Contact Name		Ti	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Ste	wards	Pr	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	esentative*	Ti	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Reque	ester Item Number	em Number Mfr Item Number Mfr Item Name NCP59749MN2ADJT 3 A, Dual-Rail VLD Programmable Softs		Mfr Item Name			Effective Date	Version	. I	Manufacturing Site	V	Veight*	UOM	Unit Type	
				OO Lin Reg w Start	rith	2023-06-08	PH1		7	4.25	mg	Each			
Ianufacturin	g Proccess Information	on													
Terminal Plating / Grid Array Material Terminal Base Alloy J-ST			STD-020 MSI	L Rating	Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cyc						eles				
Matte Tin (Sn) - annealed		CU A	CU Alloy 1				260	С		30	secono	ls 3			
omments															
vel 1 - maximun	n time at peak temperature	e during solder	ring is 10-30) seconds											
or more informs	ation regarding material co	omposition ples	ase refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall apply the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.23	mg	Supplier	Silicon (Si)	7440-21-3		1.23	mg
Die Attach	0.26	mg	Supplier	Silver (Ag)	7440-22-4		0.195	mg
			Supplier	Epoxy resins	129915-35-1		0.065	mg
Lead Frame	31.06	mg	Supplier	Copper (Cu)	7440-50-8		31.06	mg
Mold Compound-Black	39.27	mg		Epoxy Phenol Resin	proprietary data		4.1234	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.1466	mg
Plating	1.35	mg	Supplier	Tin (Sn)	7440-31-5		1.35	mg
Wire Bond - Au	1.08	mg	Supplier	Gold (Au)	7440-57-5		1.08	mg